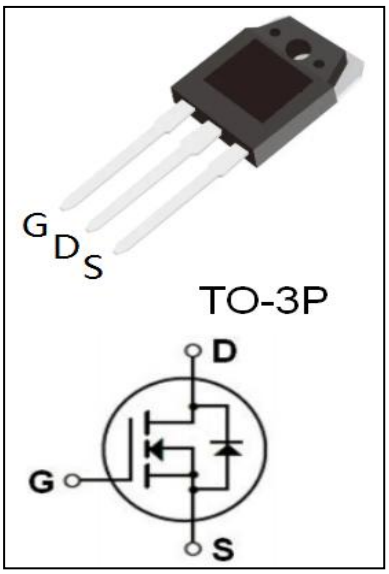
SMP18N50

500V N-Channel MOSFET



● **Features：**

- 18.0A, 500V, $R_{DS(on)(Typ)}$ =270mΩ@V_{GS}=10V
- Low Gate Charge
- Low C_{rss}
- 100% Avalanche Tested
- Fast Switching
- Improved dv/dt Capability

● **Application:**

- High Frequency Switching Mode Power Supply
- Active Power Factor Correction

Absolute Maximum Ratings(Tc=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	500	V
I_D	Drain Current - Continuous(Tc=25°C)	18.0*	A
	- Continuous(Tc=100°C)	11.38*	A
I_{DM}	Drain Current -Pulsed (Note1)	72*	A
V_{GSS}	Gate-Source Voltage	±30	V
E_{AS}	Single Pulsed Avalanche Energy （Limit Reference Value） (Note2)	862	mJ
I_{AR}	Avalanche Current (Note1)	14.0	A
dv/dt	Peak Diode Recovery dv/dt (Note3)	4.5	V/ns
P_D	Power Dissipation(T_C =25°C)	244	W
	-Derate above 25°C	1.95	W/°C
Tj	Operating Junction Temperature	150	°C
Tstg	Storage Temperature Range	-55 to+150	°C

* Drain Current Limited by Maximum Junction Temperature.

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	0.51	°C /W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	50	°C /W

Electrical Characteristics(Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditons	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-source Breakdown Voltage	V_{GS}=0V ,I_D=250μA	500	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=500V,V_{GS}=0V	--	--	1	μA
		V_{DS}=400V,Tc=125°C	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current,Forward	V_{GS}=+30V, V_{DS}=0V	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current,Reverse	V_{GS}=-30V, V_{DS}=0V	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}= V_{GS}, I_D=250μA	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS}=10 V, I_D=9.0A	--	270	350	mΩ
g_{FS}	Forward Transconductance	V_{DS}=20 V, I_D=9.0A (Note4)	--	14	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}=25V,V_{GS}=0V, f=1.0MHz	--	2620	--	pF
C_{oss}	Output Capacitance		--	243	--	pF
C_{rss}	Reverse Transfer Capacitance		--	9.5	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 250 V, I_D = 18 A, R_G = 25 Ω (Note4,5)	--	65	--	ns
t_r	Turn-On Rise Time		--	165	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	95	--	ns
t_f	Turn-Off Fall Time		--	90	--	ns
Q_g	Total Gate Charge	V_{DS} = 400 V, I_D =18 A, V_{GS} = 10 V (Note4,5)	--	45	--	nC
Q_{gs}	Gate-Source Charge		--	12.5	--	nC
Q_{gd}	Gate-Drain Charge		--	19	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	18	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	72	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} =0V,I_S=18 A	--	--	1.4	V
t_{rr}	Reverse Recovery Time	V_{GS} =0V, I_S=18 A, d I_F /dt=100A/μs (Note4)	--	500	--	ns
Q_{rr}	Reverse Recovery Charge		--	5.4	--	μC

Notes:

1、Repetitive Rating:Pulse Width Limited by Maximum Junction Temperature.

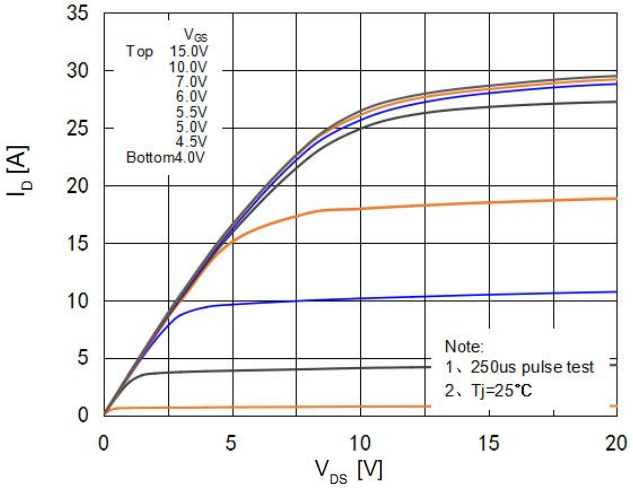
2、L = 8mH, I_{AS} =14.0A, V_{DD} = 80V, R_G = 25 Ω, Starting T_J = 25°C.

3、I_{SD}≤18.0A, di/dt≤200A/μs, V_{DD}≤BV_{DSS}, Starting T_J = 25°C.

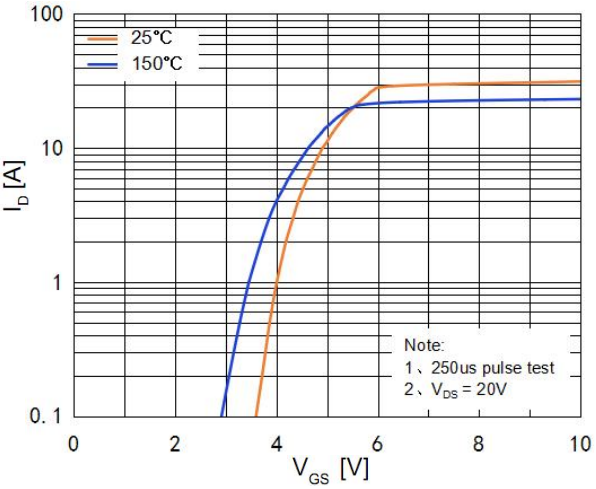
4、Pulse Test : Pulse Width ≤300 μ s, Duty Cycle≤2%.

5、Essentially Independent of Operating Temperature.

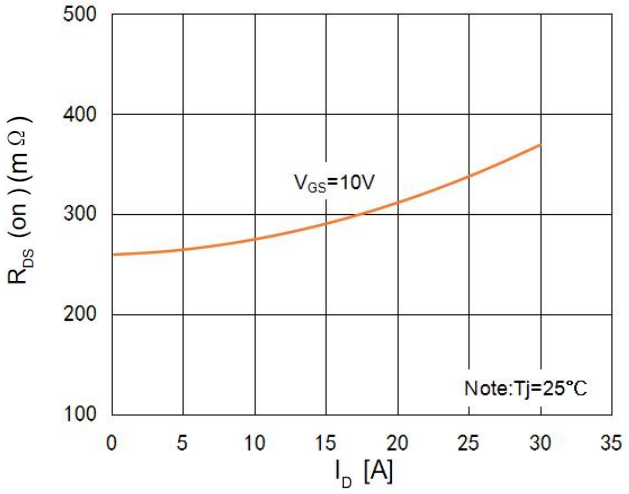
On-Regin Characteristics



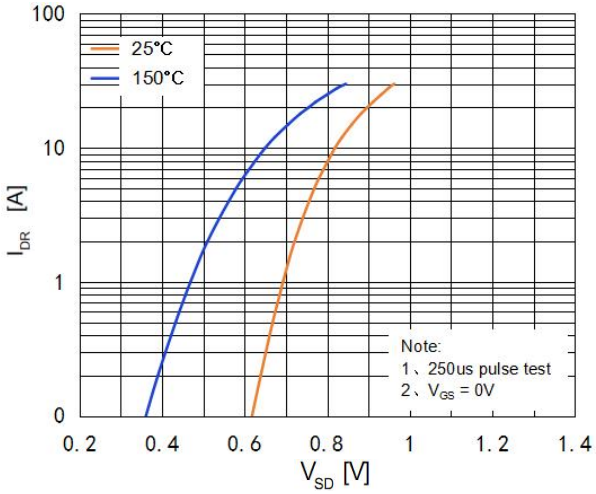
Transfer Characteristics



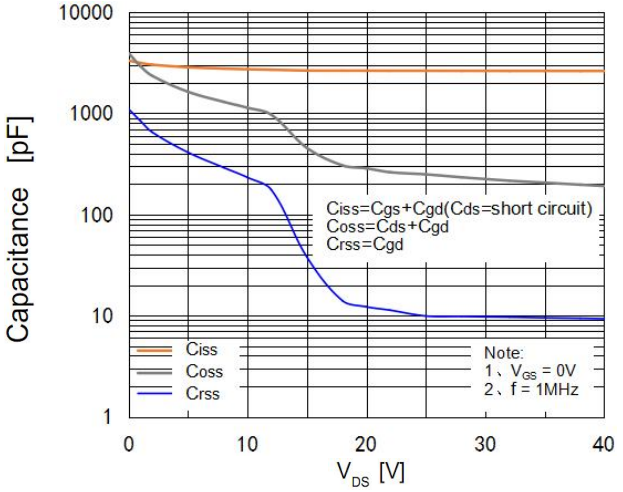
On-Resistance Variation vs. Drain Current and Gate Voltage



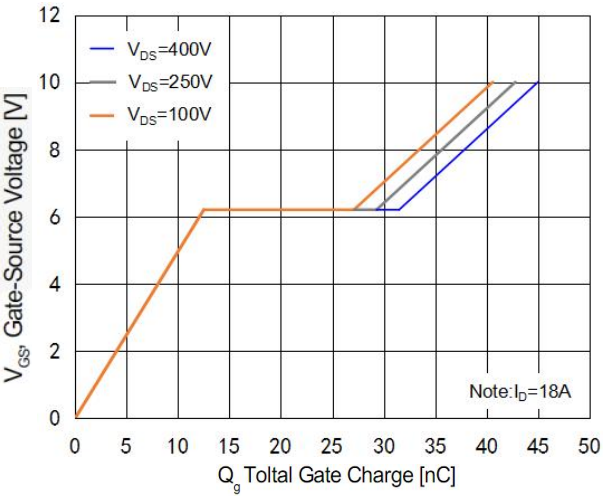
Body Diode Forward Voltage Variation vs. Source Current and Temperature



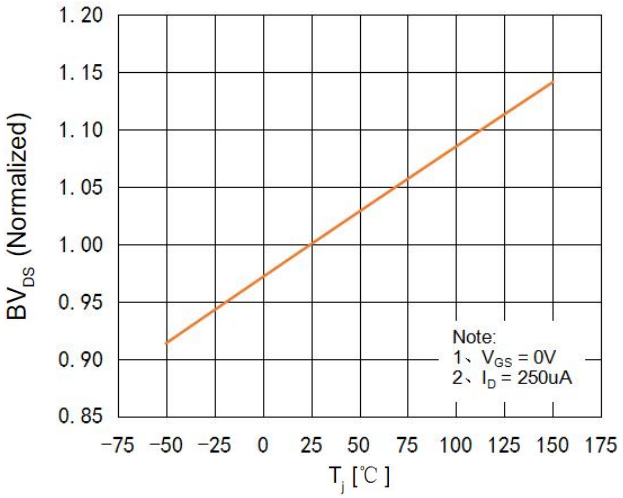
Capacitance Characteristics



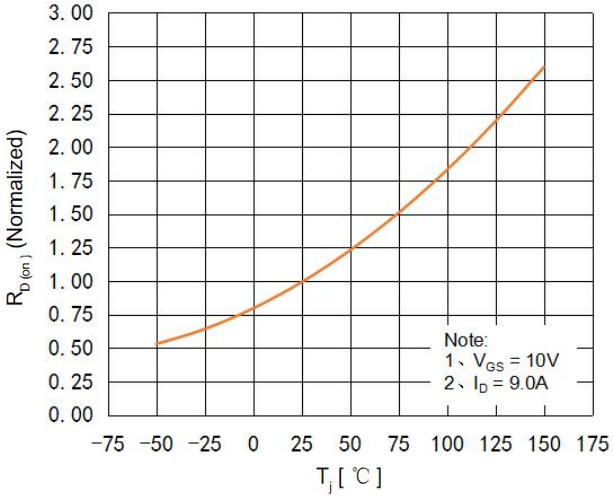
Gate Charge Characteristics



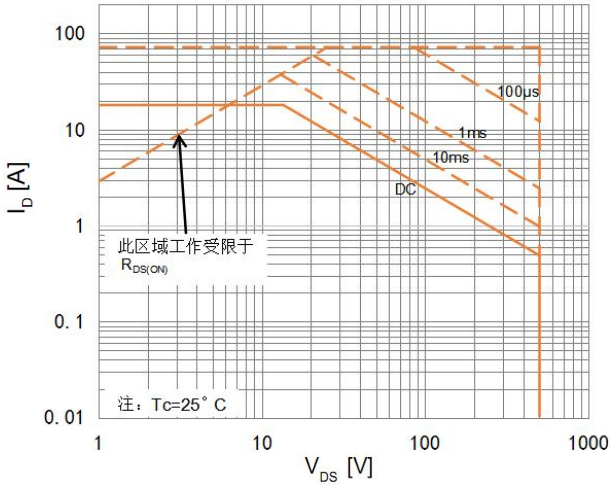
Breakdown Voltage Variation vs. Temperature



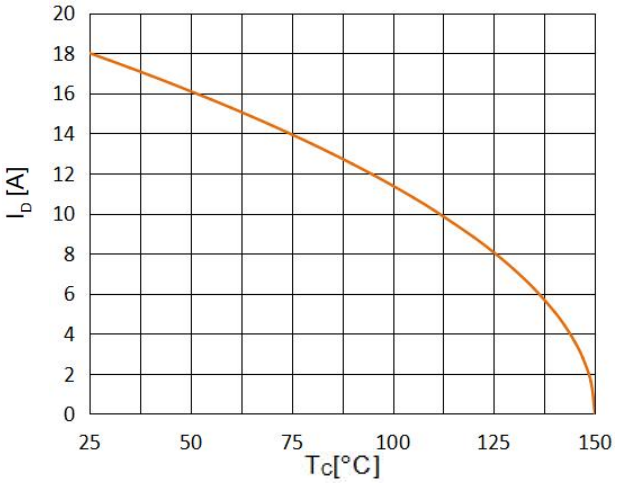
On-Resistance Variation vs. Temperature



Maximum Safe Operating Area



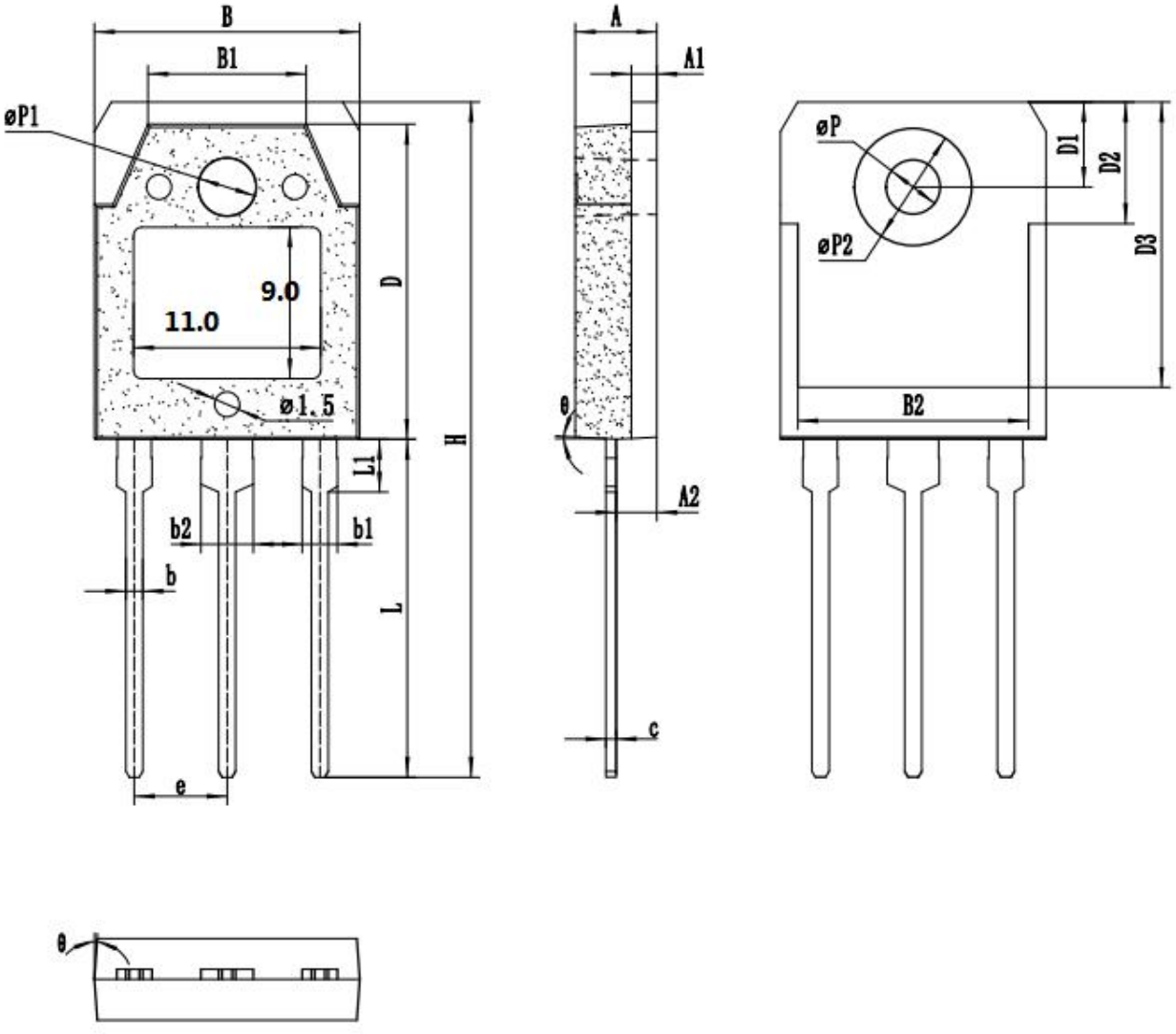
Maximum Drain Current Vs. Case Temperature



TO-3P Package Dimensions

UNIT：mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.50	4.80	5.10	D	18.00	18.50	19.00
A1	1.40	1.50	1.60	D1	4.60	5.00	5.40
A2	2.10	2.40	2.70	D2	6.70	7.10	7.50
b	0.80	1.00	1.20	D3	16.20	16.70	17.20
b1	1.90	2.10	2.30	L1	2.70	3.10	3.50
b2	2.90	3.10	3.30	L	19.20	20.20	21.20
e		5.45		H	38.40	39.90	41.40
B	15.20	15.70	16.20	ΦP	2.90	3.15	3.40
B1	9.10	9.40	9.70	ΦP1	3.15	3.40	3.65
B2	13.20	13.60	14.00	ΦP2	6.70	7.00	7.30
c	0.50	0.60	0.70	θ	3°	5°	7°



注意事项：

1、在电路设计时请不要超过器件的最大额定值，否则会影响整机的可靠性。

2、MOSFET产品为静电敏感型器件，使用时应注意采取防静电保护措施，如佩戴防静电手环、设备接地等。

3、如需安装散热片，请注意控制扭力大小及散热片的平整度。

4、该规格书由华科公司制作，并可能不定期更改，恕不另行通知。

5、如有疑问，请及时联系我司销售代表。

版本履历表：

序号	版本号	修改时间	修改记录
1	V1.0	2023-10-12	首次发行